



## Material Content Data Sheet



<b>Sales Product Name</b>		SAK-XC2368E-136F128L AA		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001025844						
<b>Package</b>		PG-LQFP-100-8		<b>Weight*</b>		759.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	56.102	7.38	7.38	73831	73831
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.01		90	
	non noble metal	zinc	7440-66-6	0.275	0.04		362	
	non noble metal	iron	7439-89-6	5.501	0.72		7239	
wire	non noble metal	copper	7440-50-8	223.351	29.39	30.16	293935	301626
	noble metal	gold	7440-57-5	3.427	0.45	0.45	4510	4510
	encapsulation	organic material	carbon black	1333-86-4	2.234	0.29		2940
encapsulation	plastics	epoxy resin	-	60.324	7.94		79388	
	inorganic material	silicondioxide	60676-86-0	384.285	50.58	58.81	505730	588058
leadfinish	non noble metal	tin	7440-31-5	9.288	1.22	1.22	12224	12224
plating	noble metal	silver	7440-22-4	2.495	0.33	0.33	3283	3283
glue	plastics	epoxy resin	-	3.128	0.41		4117	
	noble metal	silver	7440-22-4	9.385	1.24	1.65	12351	16468
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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